	Application No.	Applicant(s)
Notice of Allowability	10/617,427	GORMLEY ET AL.
	Examiner	Art Unit
	Pamela E. Perkins	2822
The MAILING DATE of this communication apperature All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIOF the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this applied or other appropriate communication GHTS. This application is subject to and MPEP 1308.	plication. If not included will be mailed in due course. THIS
<ol> <li>This communication is responsive to the after-final amendr</li> </ol>	nent filed on 29 December 2005.	
2. $\boxtimes$ The allowed claim(s) is/are <u>1-35</u> .		
<ul> <li>3. Acknowledgment is made of a claim for foreign priority una)</li> <li>a) All b) Some* c) None of the:</li> <li>1. Certified copies of the priority documents have</li> <li>2. Certified copies of the priority documents have</li> </ul>	been received.	·
3. Copies of the certified copies of the priority documents have been received in this national stage application from the		
International Bureau (PCT Rule 17.2(a)).		
* Certified copies not received:		
Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application.  THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.		
4. A SUBSTITUTE OATH OR DECLARATION must be submit INFORMAL PATENT APPLICATION (PTO-152) which give	itted. Note the attached EXAMINER es reason(s) why the oath or declara	S AMENDMENT or NOTICE OF tion is deficient.
5. CORRECTED DRAWINGS ( as "replacement sheets") must be submitted.		
(a) 🔲 including changes required by the Notice of Draftsperson's Patent Drawing Review ( PTO-948) attached		
1)  hereto or 2)  to Paper No./Mail Date		
(b) including changes required by the attached Examiner's Paper No./Mail Date		
Identifying indicia such as the application number (see 37 CFR 1. each sheet. Replacement sheet(s) should be labeled as such in the		
<ol> <li>DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT I</li> </ol>	sit of BIOLOGICAL MATERIAL n FOR THE DEPOSIT OF BIOLOGICA	nust be submitted. Note the AL MATERIAL.
Attachment(s) 1. ☐ Notice of References Cited (PTO-892)	5   Notice of Informal D	start Application (DTO 450)
2. ☐ Notice of Neierences Cited (FTO-092)  2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)	6. ☐ Interview Summary	atent Application (PTO-152)
	Paper No./Mail Dat	e
<ol> <li>Information Disclosure Statements (PTO-1449 or PTO/SB/0)</li> <li>Paper No./Mail Date</li> </ol>	8), 7. 🗌 Examiner's Amendn	nent/Comment
Examiner's Comment Regarding Requirement for Deposit of Biological Material	8.   Examiner's Stateme	ent of Reasons for Allowance
	9. 🔲 Other	

Art Unit: 2822

## **DETAILED ACTION**

This office action is in response to the filing of the after-final amendment on 29 December 2005. Claims 1-35 are pending; claims 36-38 have been cancelled.

## Allowable Subject Matter

Claims 1-35 are allowed.

## Reasons for Allowance

The following is an examiner's statement of reasons for allowance: prior art does not disclose teach or suggest applying a support layer to each bridging portion of a buried insulating layer the support layer extending across each trench, and being applied to each bridging portion of the buried insulating layer prior to the bridging portion being exposed by a communication opening through a handle layer for supporting the bridging portion fro preventing rupturing of the buried insulating layer when the buried insulating layer is exposed by the communication opening through the handle layer..

For example, Gormley (6,818,564) discloses a method for forming a micromechanical component in a semiconductor wafer where a membrane layer supported on a handle layer with a buried insulating layer disposed between the membrane layer and the handle layer, the micro-mechanical component being formed in the membrane layer, and a communicating opening extending through the handle layer and the buried insulating layer exposing the micro-mechanical component; forming at least one trench extending through the membrane layer for defining the micro-mechanical component therein, each trench exposing a portion of the buried insulating layer bridging the trench.

However, Gormley does not disclose, anticipate, teach, or suggest applying a support layer to each bridging portion of a buried insulating layer the support layer extending across each trench, and being applied to each bridging portion of the buried insulating layer prior to the bridging portion being exposed by a communication opening through a handle layer for supporting the bridging portion fro preventing rupturing of the buried insulating layer when the buried insulating layer is exposed by the communication opening through the handle layer.

Peeters et al. (6,300,665) disclose a method for forming a micro-mechanical component in a semiconductor wafer where a membrane layer supported on a handle layer with a buried insulating layer disposed between the membrane layer and the handle layer, the micro-mechanical component being formed in the membrane layer, and a communicating opening extending through the handle layer and the buried insulating layer exposing the micro-mechanical component; forming at least one opening extending for defining the micro-mechanical component therein, each opening exposing a portion of the membrane layer bridging the openings, applying a support layer to each bridging portion, the support layer extending across each opening, and being applied to each bridging portion prior to the bridging portion being exposed by the communicating opening through the handle layer.

However, Peeters et al. do not disclose, anticipate, teach or suggest applying a support layer to each bridging portion of a buried insulating layer the support layer

Art Unit: 2822

extending across each trench, and being applied to each bridging portion of the buried insulating layer prior to the bridging portion being exposed by a communication opening through a handle layer for supporting the bridging portion fro preventing rupturing of the buried insulating layer when the buried insulating layer is exposed by the communication opening through the handle layer.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Pamela E. Perkins whose telephone number is (571) 272-1840. The examiner can normally be reached on Monday thru Friday, 8:30am to 5:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on (571) 272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Application/Control Number: 10/617,427

Art Unit: 2822

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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SUPERVISORY PATENT EXAMINER

Page 5